

40V 2.0mohm N-channel SGT MOSFET

Description:

This N-channel SGT MOSFET has been designed to low on-state resistance and maintain superior switching performance, especial for high efficiency power management applications.

Features:

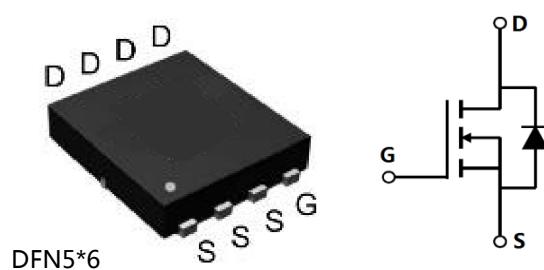
- Low $R_{DS(ON)}$
- RoHS compliant ^(Note 1)
- Halogen-free ^(Note 1)
- 100% UIS Tested

Applications:

- Battery Management System
- Motor Drivers
- DC-DC Converter

Key Performance Parameters:

Parameter	Value	Unit
V_{DS}	40	V
$R_{DS(ON), \max} @ V_{GS} = 10V$	2.0	mΩ
I_D	200	A



Ordering Information:

Ordering Code	Package Type	Marking Code	Form	Packing
MPGJ04R017	DFN5*6	MPGJ04R017	-	-

Notes:

1. Contact MP sales for detail information

Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Value	Units
V_{DS}	Drain-Source Voltage	40	V
I_D	Drain Current - Continuous ($T_C = 25^\circ\text{C}$) ^(Note 1)	200	A
	Drain Current - Continuous ($T_C = 100^\circ\text{C}$)	125	A
I_{DM}	Drain Current - Pulsed ^(Note 2)	600	A
V_{GS}	Gate-Source Voltage	± 20	V
E_{AS}	Single Pulsed Avalanche Energy ^(Note 3)	552	mJ
P_D	Power Dissipation ($T_C = 25^\circ\text{C}$)	130	W
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Value	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Steady-State	1.04	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Steady State ^(Note 4)	62	$^\circ\text{C/W}$

Notes:

1. The max drain current rating is silicon limited
2. Repetitive Rating: Pulse width limited by maximum junction temperature
3. $L = 0.5 \text{ mH}$, $V_{DD} = 30 \text{ V}$, $I_{AS} = 47 \text{ A}$, $R_G = 25 \Omega$, Starting $T_J = 25^\circ\text{C}$
4. Mount on minimum PCB layout

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}} = 0 \text{ V}$, $I_D = 250 \mu\text{A}$	40			V
$I_{\text{DS}(\text{SS})}$	Zero Gate Voltage Drain Current	$V_{\text{DS}} = 40 \text{ V}$, $V_{\text{GS}} = 0 \text{ V}$,			1	μA
I_{GSS}	Gate Leakage Current	$V_{\text{GS}} = \pm 20 \text{ V}$, $V_{\text{DS}} = 0 \text{ V}$			± 100	nA
$V_{\text{GS}(\text{TH})}$	Gate Threshold voltage	$V_{\text{DS}} = V_{\text{GS}}$, $I_D = 250 \mu\text{A}$	2	3	4	V
$R_{\text{DS}(\text{ON})}$	Drain-Source on-state resistance	$V_{\text{GS}} = 10 \text{ V}$, $I_D = 50 \text{ A}$		1.7	2.0	$\text{m}\Omega$
		$V_{\text{GS}} = 6 \text{ V}$, $I_D = 50 \text{ A}$		2.5	3.0	$\text{m}\Omega$

Dynamic Characteristics

C_{ISS}	Input Capacitance	$V_{\text{DS}} = 25 \text{ V}$, $V_{\text{GS}} = 0 \text{ V}$, $F = 1 \text{ MHz}$		6240		pF
C_{OSS}	Output Capacitance			1520		pF
C_{RSS}	Reverse Transfer Capacitance			24		pF
R_G	Gate Resistance	$F = 1 \text{ MHz}$		4.2		Ω

Switching Characteristics

$T_{\text{D}(\text{ON})}$	Turn On Delay Time	$V_{\text{DD}} = 20 \text{ V}$, $I_D = 35 \text{ A}$, $V_{\text{GS}} = 10 \text{ V}$, $R_G = 2.0 \Omega$		13.6		nS
T_R	Rise Time			10.2		nS
$T_{\text{D}(\text{OFF})}$	Turn Off Delay Time			51.6		nS
T_F	Fall Time			22.2		nS
Q_G	Total Gate Charge	$V_{\text{DD}} = 20 \text{ V}$, $I_D = 35 \text{ A}$, $V_{\text{GS}} = 10 \text{ V}$		73		nC
Q_{GS}	Gate-Source Charge			28		nC
Q_{GD}	Gate-Drain Charge			11		nC

Drain-Source Diode Characteristics and Maximum Ratings

I_S	Maximum Continuous Body-Diode Forward Current		200		A
I_{SM}	Maximum Pulsed Body-Diode Forward Current (NOTE 1)		600		A
V_{SD}	Diode Forward Voltage	$V_{\text{GS}} = 0 \text{ V}$, $I_S = 35 \text{ A}$		1.3	V
T_{RR}	Reverse recovery time	$V_{\text{DD}} = 35 \text{ V}$, $I_D = 35 \text{ A}$, $di/dt = 100 \text{ A}/\mu\text{s}$		76	ns
Q_{RR}	Reverse recovery charge			125.4	nC
I_{RRM}	Peak Reverse Recovery Current			2.8	A

Electrical Characteristics Diagrams

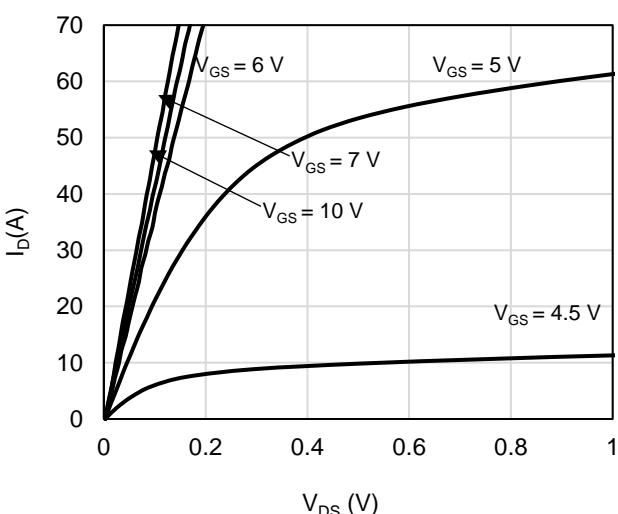


Figure 1: On-Region Characteristics

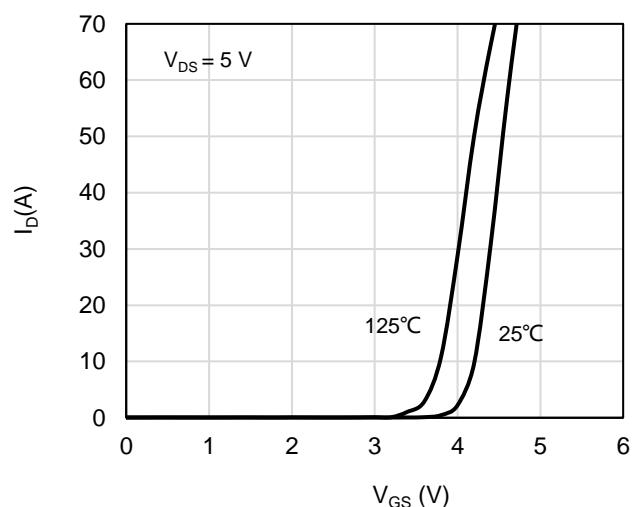


Figure 2: Transfer Characteristics

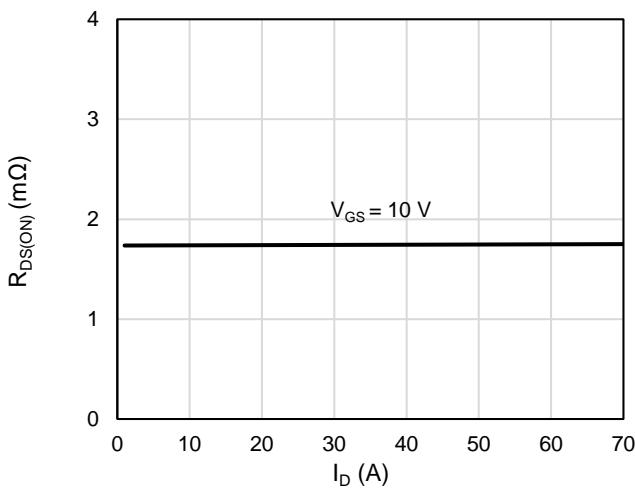


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

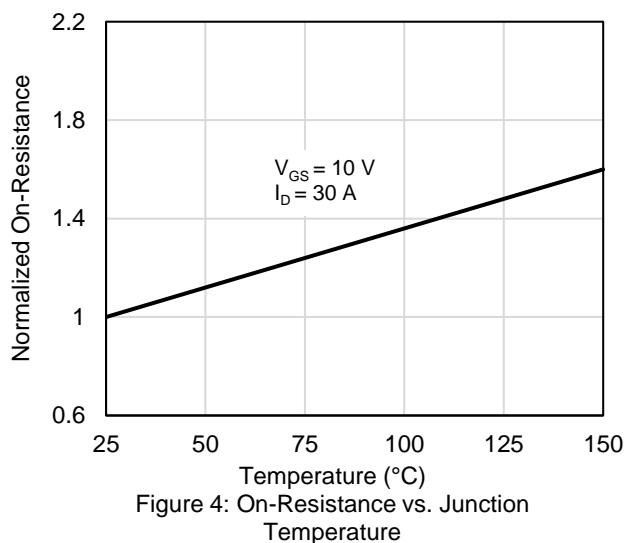


Figure 4: On-Resistance vs. Junction Temperature

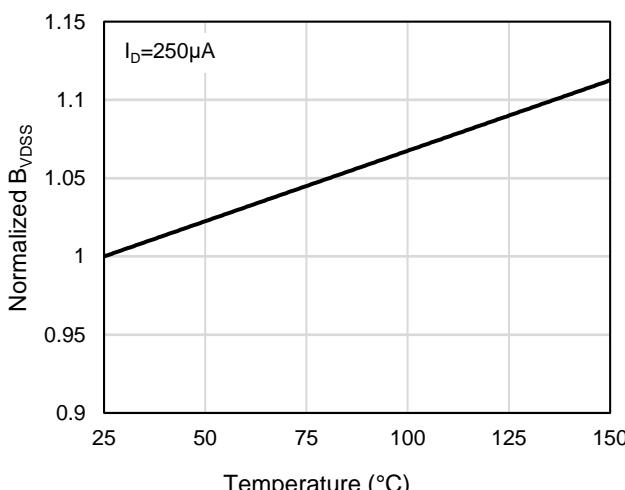


Figure 5: Breakdown Voltage vs. Junction Temperature

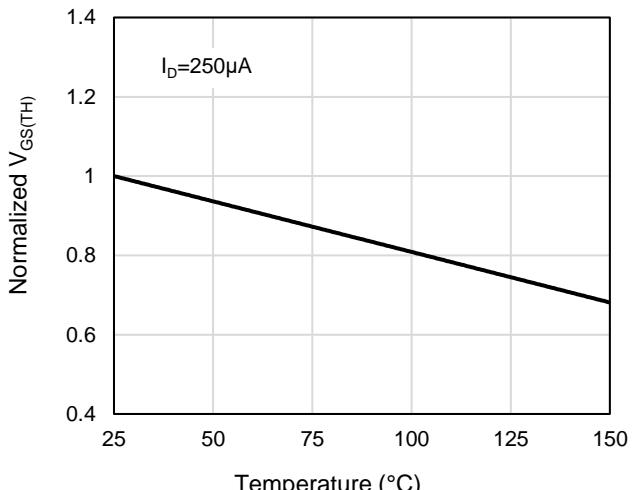


Figure 6: Threshold Voltage vs. Junction Temperature

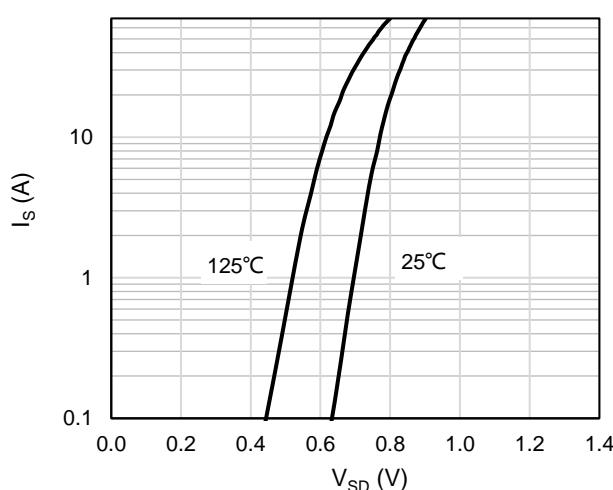


Figure 7: Body-Diode Characteristics

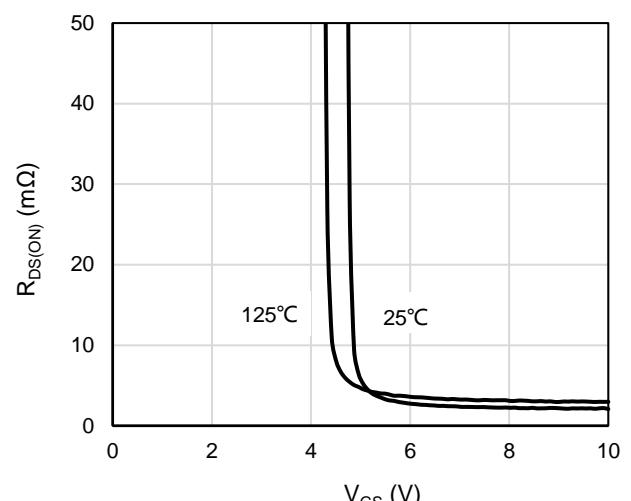


Figure 8: On-Resistance vs. Gate-Source Voltage

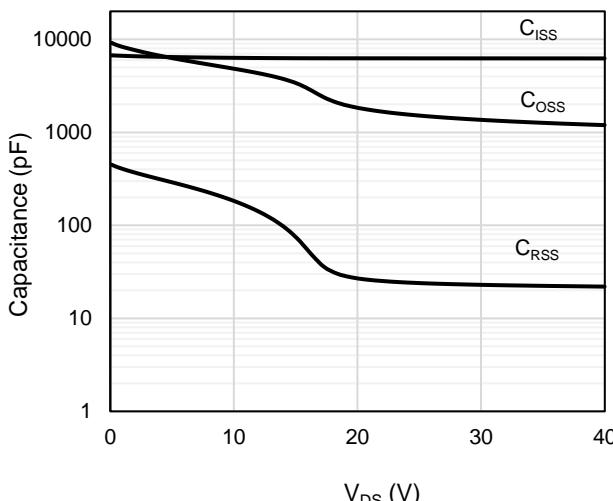


Figure 9: Capacitance Characteristics

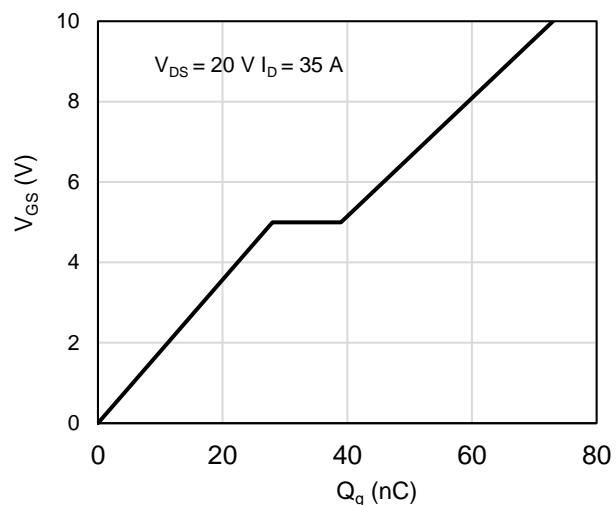


Figure 10: Gate-Charge Characteristics

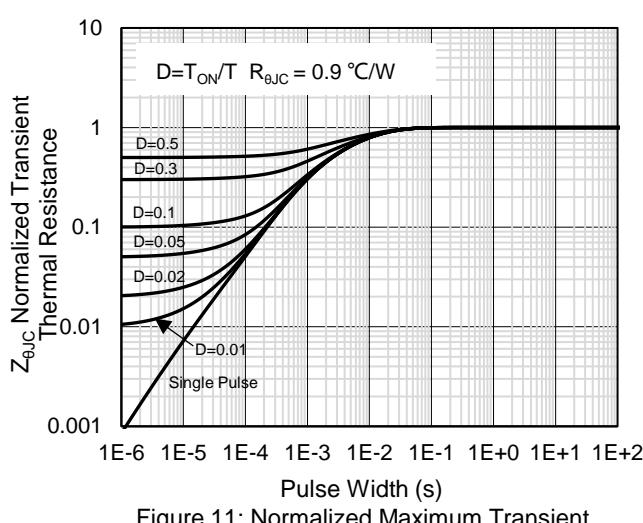


Figure 11: Normalized Maximum Transient Thermal Impedance

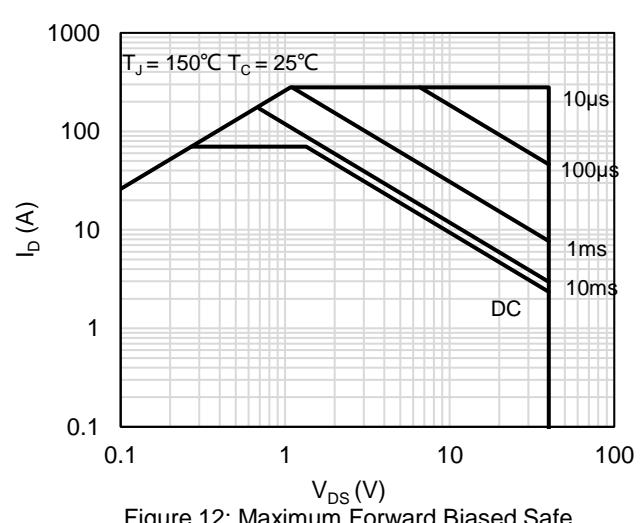
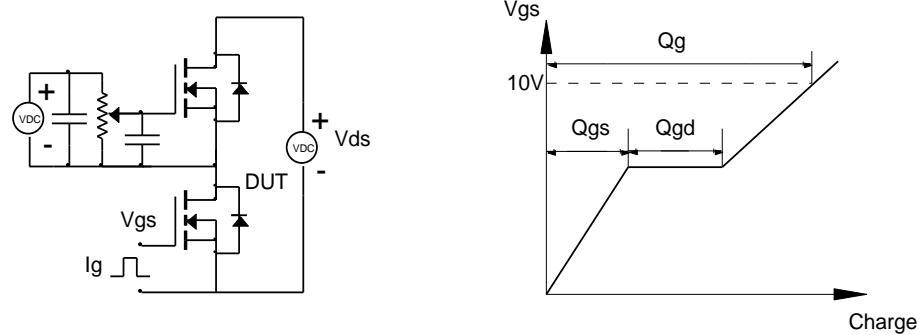


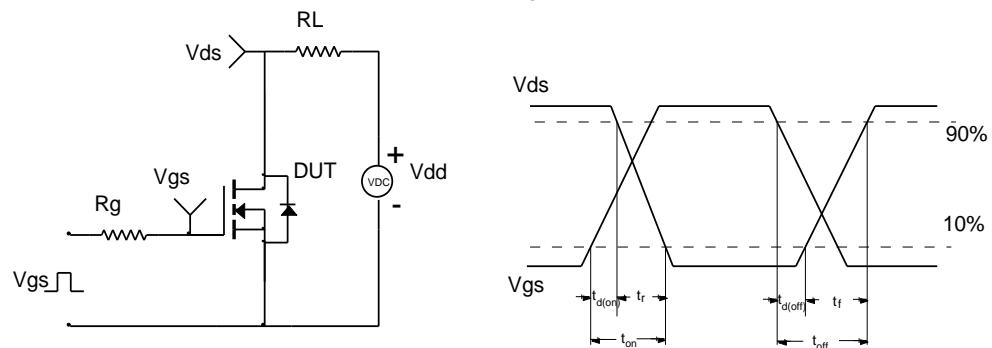
Figure 12: Maximum Forward Biased Safe Operating Area

Test Circuit and Waveform

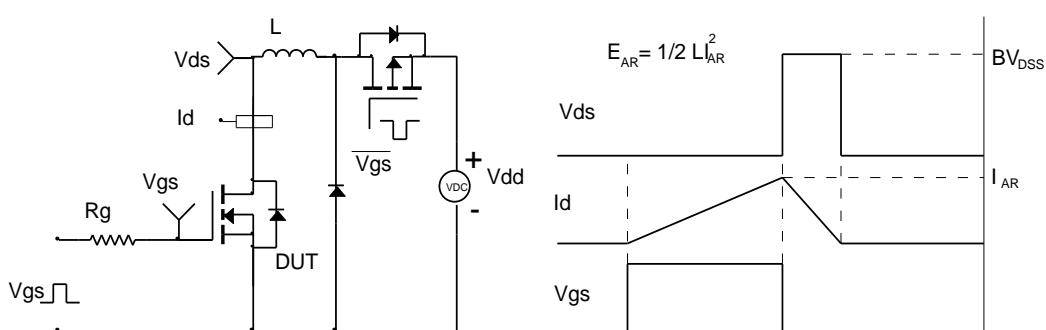
Gate Charge Test Circuit & Waveform



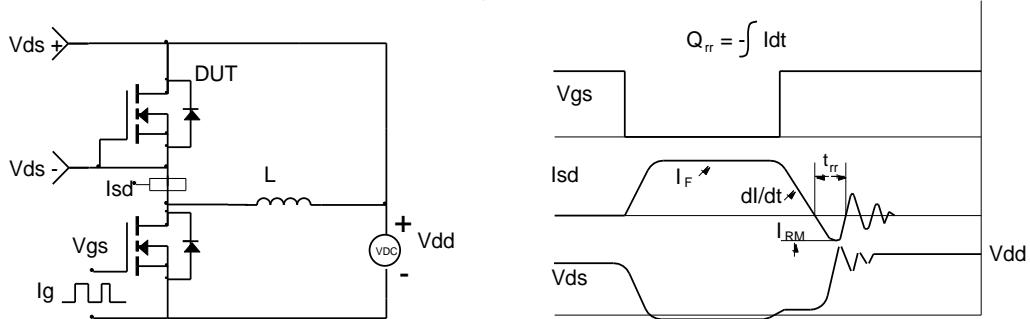
Resistive Switching Test Circuit & Waveforms



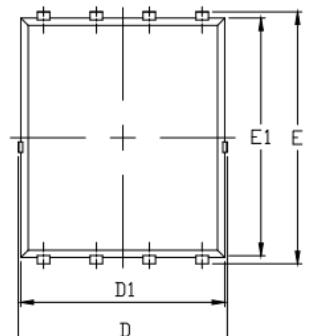
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



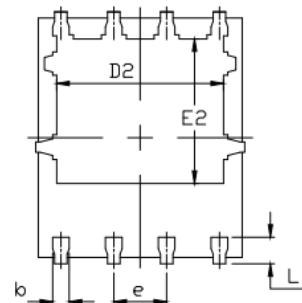
Diode Recovery Test Circuit & Waveforms



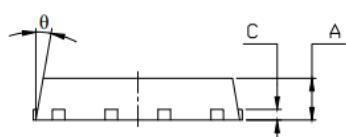
Package Outlines



Top View



Bottom View



Side View

Power56			
DIM.	MIN.	MAX.	TYP.
A	0.95	1.05	1.00
b	0.30	0.50	0.40
C	0.254		
D	5.02		
D1	4.80	5.00	4.90
D2	3.91	4.11	4.01
E	5.95	6.15	6.05
E1	5.60	5.90	5.75
E2	3.38	3.58	3.48
e	1.27REF		
L	0.45	0.65	0.55
θ	10°		

Revision History

Revision	Release Date	Remark
Rev.1.0	2022/10/13	Initial Release